

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KATSUYOSHI HARADA	02/21/2018
SATOSHI SHIMAMOTO	02/21/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HITACHI KOKUSAI ELECTRIC INC.
<b>Street Address:</b>	15-12, NISHI-SHIMBASHI 2-CHOME
<b>Internal Address:</b>	MINATO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	105-8039
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15933085
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(215)568-6499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	215-568-6400
<b>Email:</b>	mschon@vklaw.com
<b>Correspondent Name:</b>	VOLPE AND KOENIG, P.C.
<b>Address Line 1:</b>	UNITED PLAZA
<b>Address Line 2:</b>	30 SOUTH 17TH STREET, 18TH FLOOR
<b>Address Line 4:</b>	PHILADELPHIA, PENNSYLVANIA 19103
<b>ATTORNEY DOCKET NUMBER:</b>	HITACHI18-0002251US01
<b>NAME OF SUBMITTER:</b>	GERALD B. HALT, JR.
<b>SIGNATURE:</b>	/Gerald B. Halt, Jr./
<b>DATE SIGNED:</b>	03/23/2018
<b>Total Attachments: 4</b>	
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source=0002251US01_Declaration_Assignment_EFS#page3.tif	



**COMBINED DECLARATION AND ASSIGNMENT**

With respect to the invention titled:

**METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE,  
SUBSTRATE PROCESSING APPARATUS, AND RECORDING MEDIUM**

for which the undersigned has authorized or prepared an application for United States Letters Patent, U.S. Patent Application No. \_\_\_\_\_, filed on

\_\_\_\_\_,

I (the undersigned) hereby state the following:

**DECLARATION**

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than 5 years, or both.

### ASSIGNMENT

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Assignee	<u>HITACHI KOKUSAI ELECTRIC INC.</u>
Assignee State or Country of Incorporation	<u>Japan</u>
Assignee Address	<u>15-12, Nishi-shimbashi 2-chome, Minato-ku, Tokyo 105-8039, JAPAN</u>

Assignee is desirous of acquiring the entire right, title and interest in the invention, all applications for and all letters patent issued on the invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in the invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of the invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

Atty. Docket No.: HITACHI18-0002251US01

The undersigned warrants that the rights and property herein conveyed are free and clear of an encumbrance.

AND this Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, the undersigned hereby authorizes our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

**SIGNATURE SHEET FOR  
DECLARATION AND ASSIGNMENT**

Inventor's  
Name Katsuyoshi HARADA

Inventor's  
Signature Katsuyoshi Harada

Date Feb. 21, 2018

Signed at Tovama-shi, Japan  
(City and Country)

**SUPPLEMENTAL SHEET FOR  
DECLARATION AND ASSIGNMENT**

Inventor's  
Name Satoshi SHIMAMOTO

Inventor's  
Signature Satoshi Shimamoto

Date Feb. 21, 2018

Signed at Tovama-shi, Japan  
(City and Country)

**SUPPLEMENTAL SHEET FOR  
DECLARATION AND ASSIGNMENT**

Inventor's  
Name \_\_\_\_\_

Inventor's  
Signature \_\_\_\_\_

Date \_\_\_\_\_

Signed at \_\_\_\_\_  
(City and Country)